2012 IEEE
Compound Semiconductor IC Symposium

INTEGRATED CIRCUITS IN GaAs, InP, SiGe, GaN and OTHER COMPOUND SEMICONDUCTORS

October 14–17, 2012
Hyatt Regency Hotel at La Jolla, California, USA

Sponsored by the IEEE Electron Devices Society
Technically co-sponsored by the Solid State Circuits Society
and the Microwave Theory & Techniques Society

FIRST CALL FOR PAPERS

2012 CSIC Symposium

From its beginning in 1978 as the GaAs IC symposium, CSICS has evolved to become the preeminent international forum for developments in compound semiconductor integrated circuits, embracing GaAs, InP, GaN, SiGe, and more recently, CMOS technology. Coverage includes all aspects of the technology, from materials issues and device fabrication, through IC design and testing, high volume manufacturing, and system applications. The IEEE Compound Semiconductor IC Symposium (CSICS) provides the ideal forum to present your latest results in high-speed digital, analog, microwave/millimeter wave, mixed mode, and optoelectronic integrated circuits. First-time papers concerned with the utilization and application of InP, GaAs, SiGe, GaN and other compound semiconductors in military and commercial products are invited. Specific technical areas of interest include:

- Innovative RFIC Device & Circuit Concepts
- Millimeter-wave/High-Speed CMOS IC
- Circuit Design & Fabrication
- Manufacturing Technology & Cost Issues
- CAD/CAM/CAT Tools & Techniques
- IC Testing & Methodology
- Packaging Technology
- Reliability
- Advanced Device Applications
- System Applications (e.g., wireless, vehicular, RADAR, military)
- High-Speed Digital and OEIC applications

Symposium Highlights

High quality technical papers will be selected from worldwide submissions for oral presentation and publication in the Symposium Digest. Invited papers and panel sessions on topics of current importance to the Compound Semiconductor IC community will complete the program. Extended versions of selected papers from the Symposium will be published in a special issue of the *IEEE Journal of Solid State Circuits*.

Compound Semiconductor Primer Course

The Symposium will again offer the popular primer course, “Basics of Compound Semiconductor ICs,” which is an introductory-level class intended for those wishing to obtain a broad overview of RFIC and High-Speed Analog-Mixed Signal technology. The Sunday evening course will cover Si/SiGe, GaAs, InP and GaN materials and processes, BJT/HBT, HEMT & FET device operation, and both analog/microwave and digital ICs. The Course will be tailored to provide the specific background needed for participants to understand and appreciate the papers presented in the Symposium Technical Program.

Short Course

A short course will be held on Sunday, October 14, 2012. The course is currently under development and will cover current topics in the industry. Organizer: Douglas S. McPherson, Ciena, Ph: +1 613-670-3371, dmcphers@ciena.com.

Deadline for Electronic Receipt of Abstracts is Close of Business, May 7, 2012

Authors must submit an Abstract (not more than 4 pages including figures and other supporting material) of results not previously published or not already accepted by another conference. Papers will be selected on the basis of the abstract.

The abstract must concisely and clearly state:

- **a) The purpose of the work**
- **b) What specific new results have been obtained**
- **c) How it advances the state-of-the-art or the industry**
- **d) References to prior state-of-the-art**
- **e) Sub-committee preference:**
  - **Analog, RF & Microwave**
  - **Digital, Time Domain &OEIC**
  - **Millimeter-wave & High Speed CMOS**
  - **Technology & Manufacturing**

The abstract must include: the title, name(s) of the authors(s), organization(s) represented, corresponding authors’ postal and electronic addresses, and telephone and FAX numbers. Please indicate your preference for subcommittee review. The program committee will honor the authors’ preference where possible, but reserves the right to place the paper in other review categories.

Company and governmental clearances must be obtained prior to submission of the abstract.

The accepted abstracts may be used for publicity purposes. Portions of these abstracts may be quoted in magazine articles publicizing the Symposium. **Please note on the abstract if this is not acceptable.**

Authors must submit the Abstract electronically using the www.csics.org web page. Please note that the **only** accepted file format is **PDF**. Authors will be informed regarding the results of their submissions by July 7, 2012. Authors of accepted papers will be required to submit an **MS-Word version** of a 4-page camera-ready extended abstract to IEEE by August 8, 2012 for publication in the Symposium Technical Digest.

Further questions on abstract submission may be addressed to the Symposium Technical Program Chair:

Francois Colomb
Raytheon Integrated Defense Systems
Tel: 978-684-5435
fcolomb@raytheon.com

All Symposium information, including abstract submission instructions and a link to our abstract submission address is available on the CSICS website at:

http://www.csics.org

2012 Compound Semiconductor IC Symposium Exhibition

As in past years, the Symposium will sponsor an exhibition of products from various vendors of materials, IC products, processing equipment, test equipment, CAD tools, and foundry services specifically addressing the Compound Semiconductor industry. Numerous vendors will be on-hand to discuss their products and to answer questions.

Inquiries concerning the exhibits should be addressed to:

Seyed Tabatabaei
T-Optics
Tel: 707-849-2842
seyed@t-optics.com

The following members of the Technical Program Committee are available for guidance or for answering questions regarding abstract preparation:

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